

Ultra-High Performance Jitter Attenuator (JA)

Features

- Input frequency from 1 MHz to 750 MHz, gapped clock
- Output frequency from 20 MHz to 2000 MHz
- Ultra-Low RMS jitter of 20 fs (12 kHz to 20 MHz)
- LVDS/CML/LVPECL/HCSL output formats
- Output Enable/Disable Feature
- < 10 ms start-up time
- 3.2X2.5 mm 8-pin LGA package
- Single 1.8V supply with internal regulator
- Superior power supply immunity
- Temperature range: -40°C to 85°C
- Temperature extended range: -40°C to 105°C
- ESD HBM 2000V, CDM 500V
- Lead free / RoHS compliant

Applications

- SATA
- 10 GbE LAN/WAN
- SAS
- Fiber Channel
- Clock and data recovery
- PCI-Express
- Instrumentation



General Description

The MS1510 is a Jitter Attenuator powered by our Virtual Crystal™ technology that enables ultra stable fully programmable multi-GHz clocks with extremely low phase noise.

Adaptive fully autonomous DSP algorithms running in the background continuously monitor and ensure robust and consistent performance over process, voltage, and temperature variations.

The product can take any input frequency from 1 MHz to 750 MHz and generate any output frequency from 20 MHz to 2000 MHz with <1ppb. The product is configured using factory programmed NVM.

The MS1510 is manufactured in a high-volume 28 nm CMOS process and represents the most advanced node in the timing industry.

Device Information

Part Number	Package	Description
MS1510	3.2X2.5 mm 8-pin LGA	Jitter Attenuator

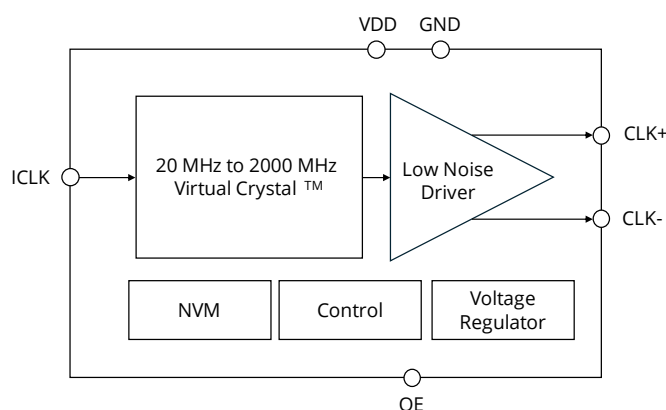


Figure 1. Functional Block Diagram

MS1510

Single Frequency Device

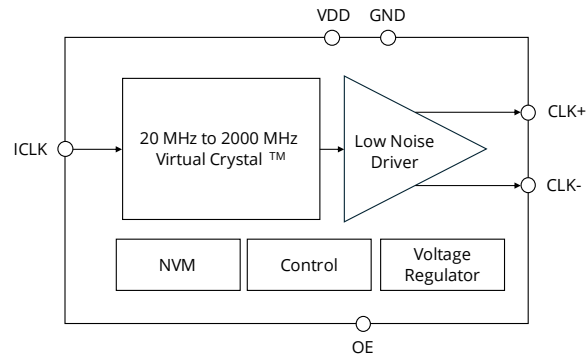


Figure 2. MS1510 Functional Block Diagram

Pin Assignment and Pin Description

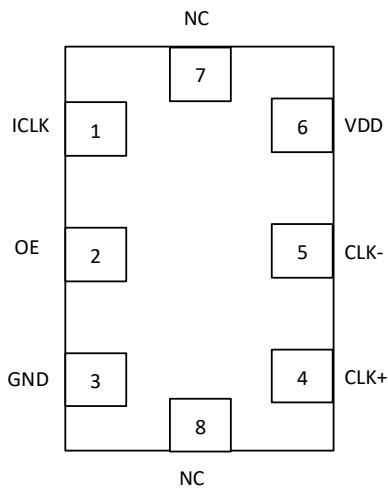


Figure 3. MS1510 Pin Assignments

Table 1. MS1510 Pin Descriptions

Pin No	Name	Description
1	ICLK	Reference CLK input
2	OE	Output Enable
3	GND	Ground
4	CLK+	Clock Output
5	CLK-	Complementary Clock Output
6	VDD	Power Supply
7	NC	No Connect
8	NC	No Connect

Specifications

Table 2. Electrical Specifications

Typical values are specified at $T_A = 25^\circ\text{C}$, $V_{DD} = 1.8\text{V}$ unless otherwise specified. All Min and Max limits are specified over the operating temperature range and voltage range with standard termination.

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
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Frequency Range

Input Frequency Range	I_{CLK}		1		750	MHz
Input Voltage Swing	I_{SWG}	AC-coupled	0.1		1.8	V _{pp} -SE
Output Frequency Range	F_{CLK}	All Output Formats	20		2000	MHz

Clock Output Jitter Characteristics

RMS Phase Jitter (12 KHz – 20 MHz)	Φ_{JITTER}	Frequency=491.52 MHz		25		fs
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Note:

Phase jitter measured on Agilent 5052B Signal Source Analyzer

Operating Voltage/Temperature Range

Supply Voltage	V_{DD}		1.71	1.8	1.89	V
Temperature Range	T_A	Industrial Temperature	-40		85	$^\circ\text{C}$
		Extended Industrial Temperature	-40		105	$^\circ\text{C}$

Current Consumption

Supply Current	I_{DD}	LVDS Output (Output Enabled)		135	162	mA
		All Other Outputs (Output Enabled)		145	174	mA
		Tristate Hi-Z (Output Disabled)		50	60	mA

Input Characteristics

Digital Input Levels (OE/FS)	V_{IH}		$0.7XV_{DD}$			V
	V_{IL}				$0.3XV_{DD}$	V
Output Enable (OE)	T_D	Output Disable Time			3	us
	T_E	Output Enable Time			20	us
Powerup Time	T_{PWR}	Time from $0.9V_{DD}$ until output frequency (F_{CLK}) within spec			10	ms

PSRR Characteristics

PSRR	$PSRR_{SPUR}$	Spurs induced by 50mV power supply ripples (All frequency, all output types)		-100		dBc
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Note:

- (1) Measured maximum spur level with 50mVpp sinusoidal signal between 50 kHz and 1 MHz applied on VDD Pin

Output Characteristics

Output Duty Cycle	DC	All Output Formats	48		52	%
Output Rise/Fall Time (20% to 80% V_{PP})	T_R / T_F	All Output Formats		65	100	ps
LVDS Output (AC Mode)	V_O	Swing (Diff)	0.5	0.7	0.9	V
LVDS Extended Output (AC Mode)	V_O	Swing (Diff)	0.8	1.2	1.6	V
CML Output (AC Mode)	V_O	Swing (Diff)	0.7	0.85	1	V
LVPECL Output (AC Mode) Integrated Termination	V_O	Swing (Diff)	1.2	1.4	1.6	V
HCSL Output Integrated Termination	V_O	Swing (Diff)	1.2	1.4	1.6	V

Table 3. Absolute Maximum Ratings

Parameter	Min	Max	Unit
1.8V Supply Voltage	-0.3	1.98	V
Digital I/O	-0.3	1.98	V
Maximum Operating Temperature		105	°C
Storage Temperature	-55	150	°C
Soldering Temperature		260	°C
Junction Temperature		150	°C
Note: Stresses that exceed what is listed in this table may cause permanent damage to the device. Exposure to conditions above the recommendations for extended periods of time may affect device reliability.			

Table 4. Environmental Compliance

Parameter	Test Condition
Mechanical Shock	MIL-STD-883, Method 2002
Mechanical Vibration	MIL-STD-883, Method 2007
Moisture Sensitivity Level (MSL)	3
Note: For additional information not listed, please contact Mixed-Signal Devices.	

Table 5. ESD Levels

Description	Description	Specification	Level
HBM ¹	Human Body Model	JEDEC JS-001	2000V
CDM ²	Charge Device Model	JEDEC JESD22-C101	500V
Notes: 1. 1000V HBM allows safe manufacturing with standard ESD control process – JEDEC document JEP155 2. 250V CDM allows safe manufacturing with standard ESD control process – JEDEC document JEP157			

Table 6. Package Thermal Information

Package	Parameter	Symbol	Value	Unit
3.2mmX2.5mm 8 pin LGA	Thermal Resistance, Junction to Ambient	θ_{JA}	80	°C/W
	Thermal Resistance, Junction to Board	θ_{JB}	40	°C/W
	Air Flow Condition		0	mps
	Maximum Junction Temperature	T_J	125	°C
Note: The thermal resistance information stated in this table is based on a standard JEDEC PCB condition. The actual thermal resistance varies depending on the customer PCB design.				

Table 7. Typical Output Phase Noise CharacteristicsVDD= 1.8V, T_A = 25°C, Output Type = CML

Offset frequency	1966.08 MHz	983.04 MHz	491.52 MHz	312.5 MHz	Unit
1 KHz	-89	-94	-99	-102	dBc/Hz
10 KHz	-119	-124	-128	-133	dBc/Hz
100 KHz	-139	-141	-151	-157	dBc/Hz
1 MHz	-149	-154	-160	-161	dBc/Hz
10 MHz	-151	-155	-159	-162	dBc/Hz
20 MHz	-150	-155	-159	-162	dBc/Hz

Typical Output Measured Phase Noise Plots

This section shows four MS1510 performance plots.

Measurement parameters are: VDD = 1.8 V, TA = 25°C, Output Type = CML.

The plots were captured using an Agilent 5052B Signal Source Analyzer.

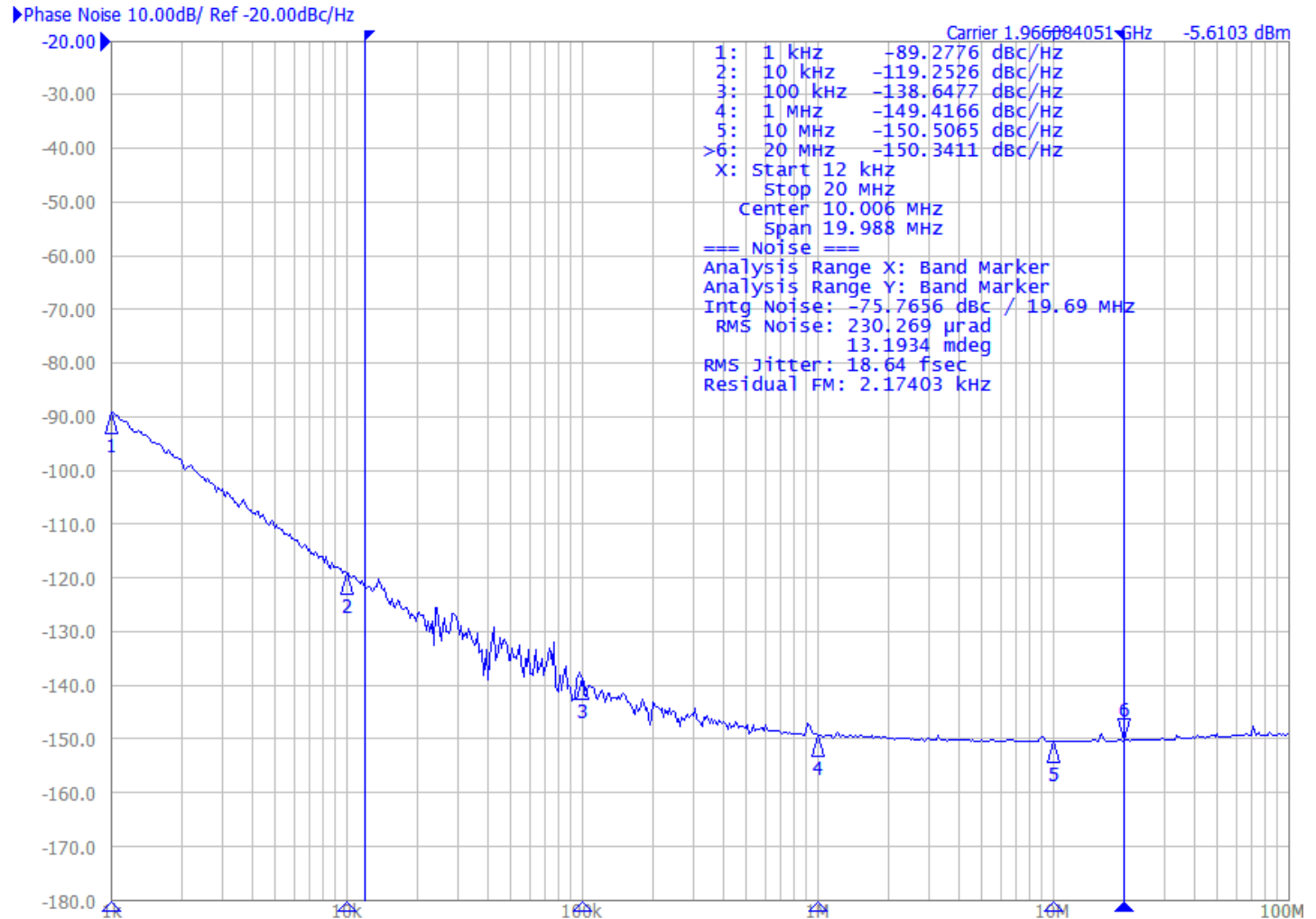


Figure 4. Carrier: 1966.08 MHz

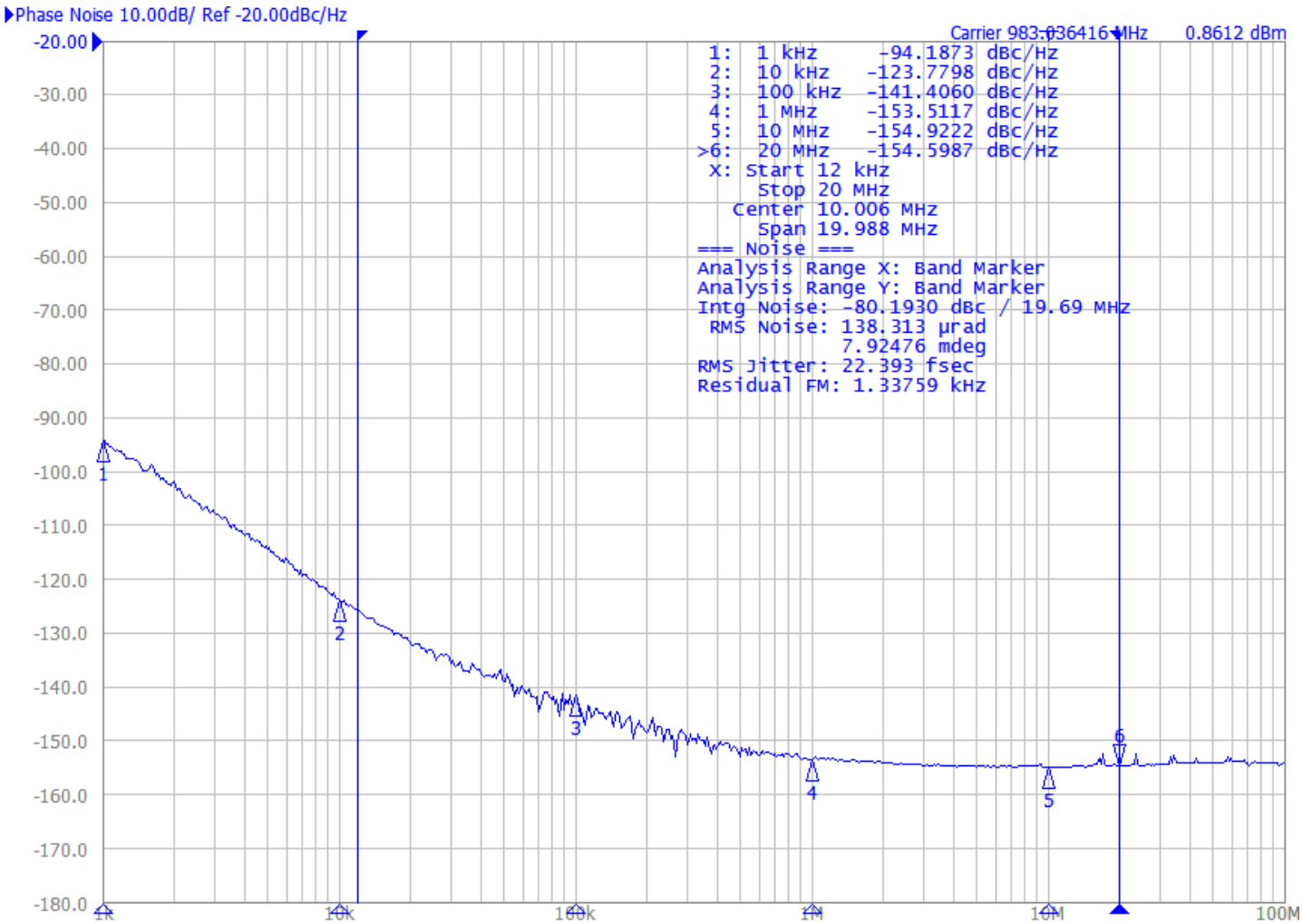


Figure 5. Carrier: 983.04 MHz

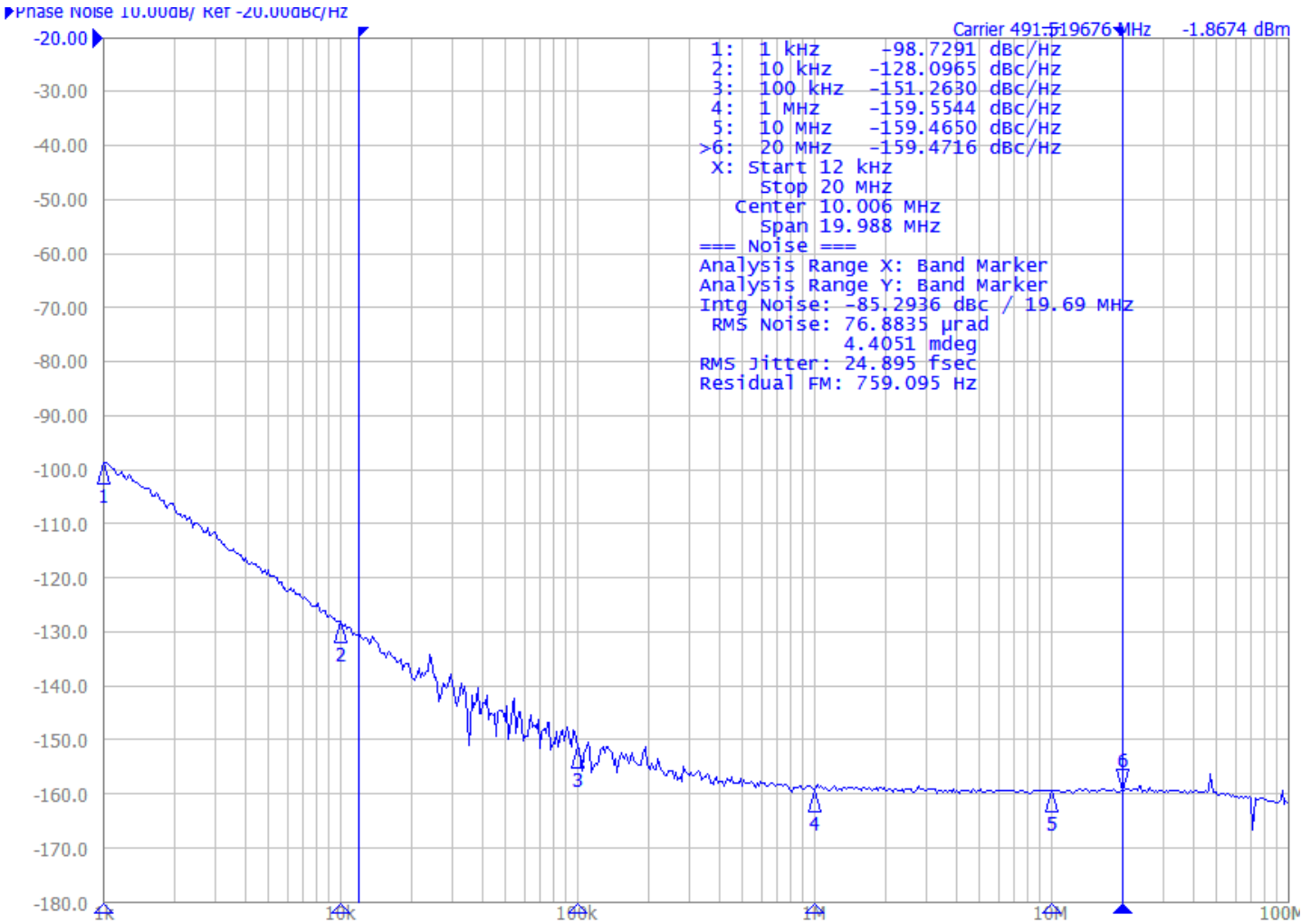


Figure 6. Carrier: 491.52 MHz

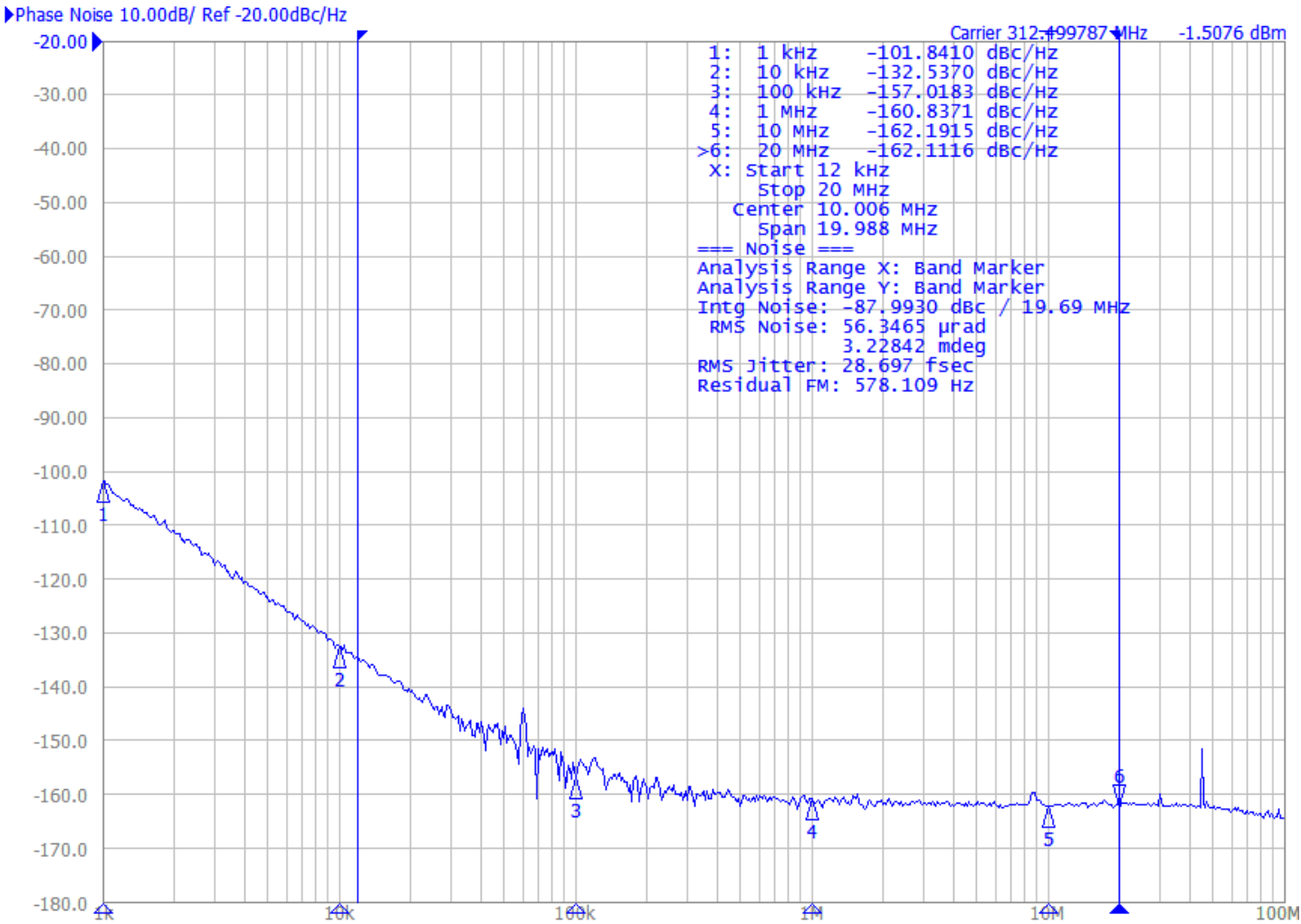


Figure 7. Carrier: 312.5 MHz

Overview

The MS1510 is a single channel high-performance Jitter Attenuator that offers exceptional capabilities in the generation of an ultra-low phase noise clock, making it an ideal solution for next-generation communication systems and base stations. This device can produce one differential output clock synchronized to the reference clock input with input frequency ranging from 1MHz to 750MHz single-ended, and gapped clock support. The MS1510 boasts an output frequency range of 20MHz to 2GHz and a remarkably low RMS jitter of 20fs (12KHz to 20MHz), making it one of the most reliable and precise devices available.

The device's programmability is configured by on-chip non-volatile memory (NVM). This attribute permits the MS1510 to provide great flexibility and ease of use in a broad range of applications, including telecommunications, networking, and test and measurement equipment.

Functional Description

MS1510 is an all-digital Phase-Locked Loop (PLL) that incorporates a range of features to enable jitter attenuation and programmable multiplication of input frequency. It receives one reference clock input and generates any multiplication of the input clock using fractional multipliers and high-speed output divider. The device can output various formats, such as LVDS, CML, LVPECL, and HCSL.

1. Frequency Configuration

The frequency configuration of the PLL is programmable through the serial interface and can also be stored in non-volatile memory. The combination of fractional frequency multiplication (M/N) and integer output division (Rn) allows the generation of any output frequency on any of the outputs. Fractional multiplication ratio and output divider ratio values can be easily calculated by the EZ-cleaner GUI utility.

2. PLL loop bandwidth

The PLL loop bandwidth determines the amount of input clock jitter attenuation. Register configurable PLL loop bandwidth settings in the range of 0.01 Hz to 4 kHz are available for selection in the EZ-cleaner GUI utility. Since the loop bandwidth is controlled digitally, the PLL will always remain stable with less than 0.1 dB of peaking regardless of the loop bandwidth selection.

Operation Modes

Free Running Mode (Default Mode)

After initialization, MS1510 will enter free running mode. In this mode, the device generates an output clock using multiplication factor stored in the on-chip NVM. The frequency accuracy of the generated output clock tracks the frequency accuracy of the input reference. For example, if the input frequency is 156.25 MHz (+/- 10ppm) and the stored multiplication factor is 33/32, the output frequency would be 161.1328125 MHz (+/- 10ppm).

Lock Acquisition Mode.

Upon completion of the configuration process, the MS1510 will transition into the lock acquisition mode. This mode comprises two stages: fast acquisition and narrow acquisition. In the first stage, the loop bandwidth is widened to facilitate a speedy initial acquisition process. Following this, the bandwidth is narrowed as the device completes the lock.

Output

MS1510 supports CML, LVDS, LVPECL, and HCSL output formats. The output enable, OE, is active HI. When OE is LOW, MS1510 output will be High Z but the loop will stay locked.

Output Terminations

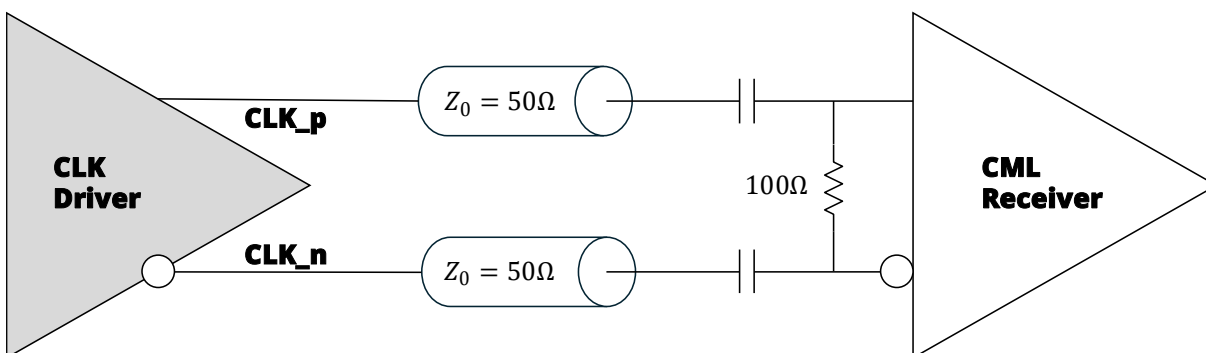


Figure 8. AC-Coupled CML

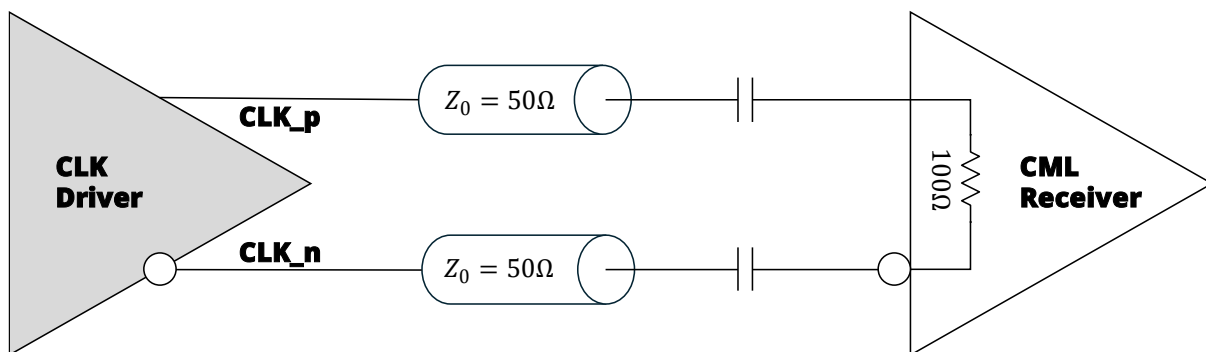


Figure 9. AC-Coupled CML (Receiver Termination)

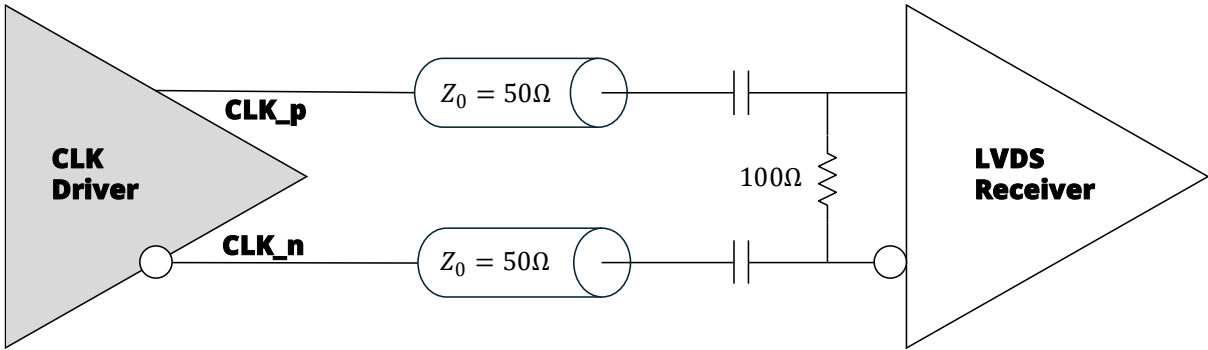


Figure 10. AC-Coupled LVDS

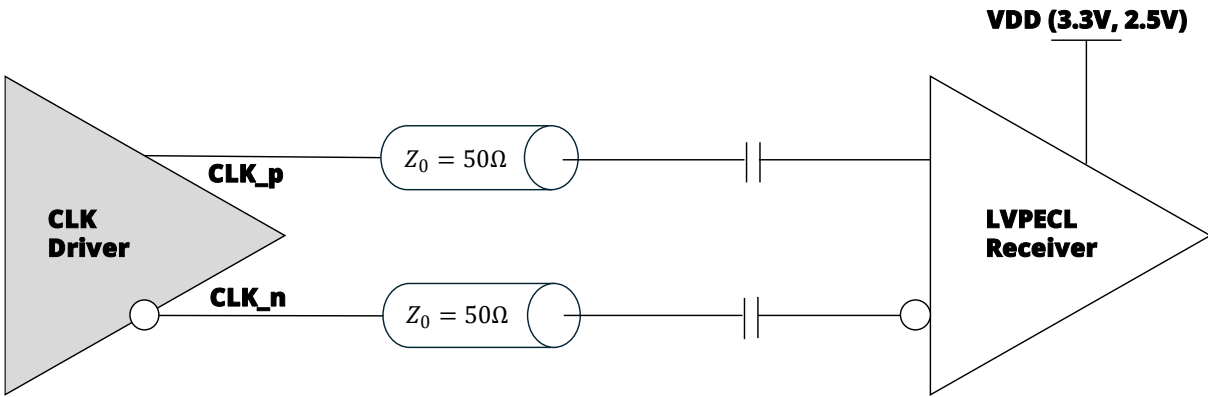


Figure 11. AC-Coupled LVPECL (Integrated Termination)

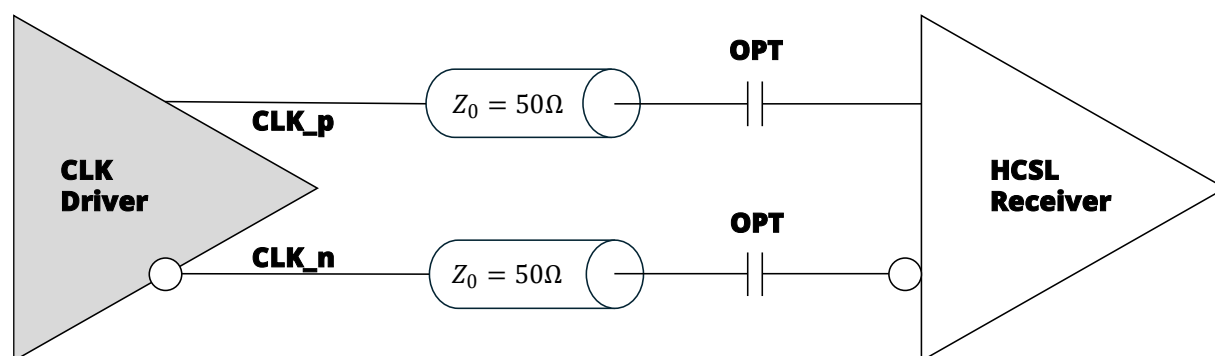


Figure 12. HCSL (Integrated Termination)

Packaging Information

Figure 13 shows the MS1510 packaging drawing.

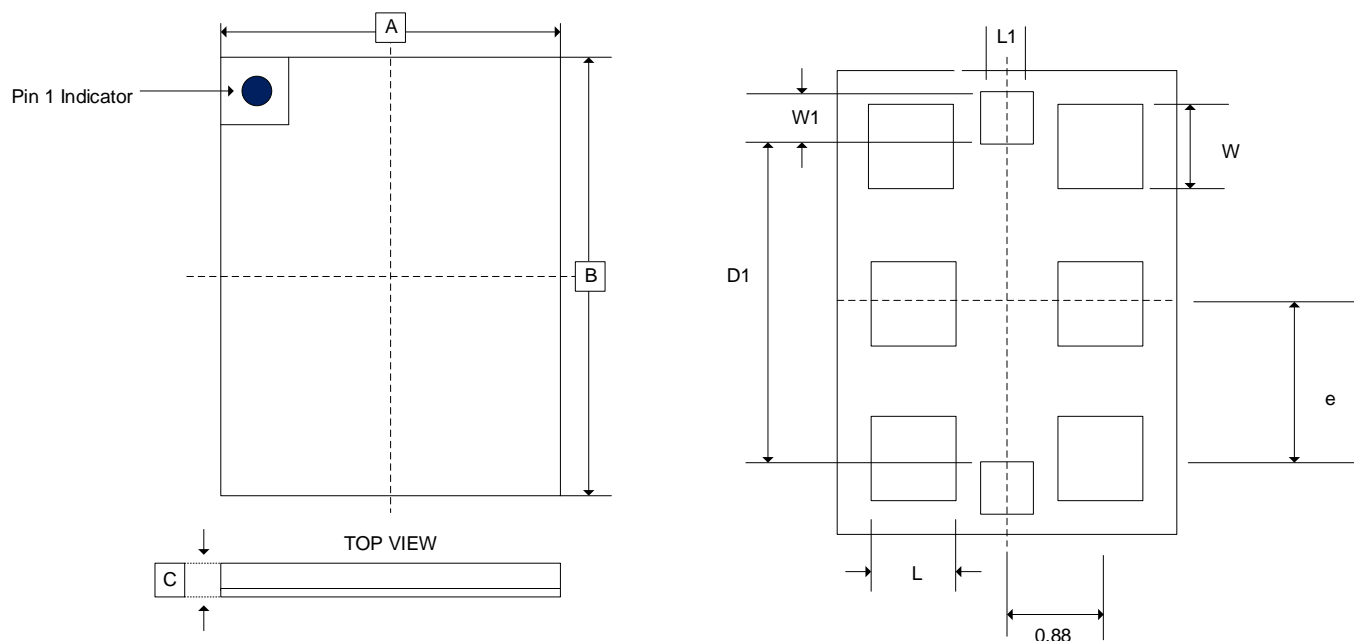


Figure 13. MS1510 Packaging Drawing (3.2mm x 2.5 mm)

Table 8. MS1510 Packaging Dimensions

Dimensions	Min	Nom	Max
A	2.5 BSC		
B	3.2 BSC		
C	0.806	0.946	1.1
W	0.55	0.6	0.65
L	0.5	0.55	0.6
W1	0.35	0.4	0.45
L1	0.35	0.4	0.45
e	1.1 BSC		
D1	2.2 BSC		
Package Edge Tolerance	0.1		
Mold Flatness	0.1		
Coplanarity	0.08		

Packaging Land Pattern

Figure 14 shows the MS1510 PCB land pattern.

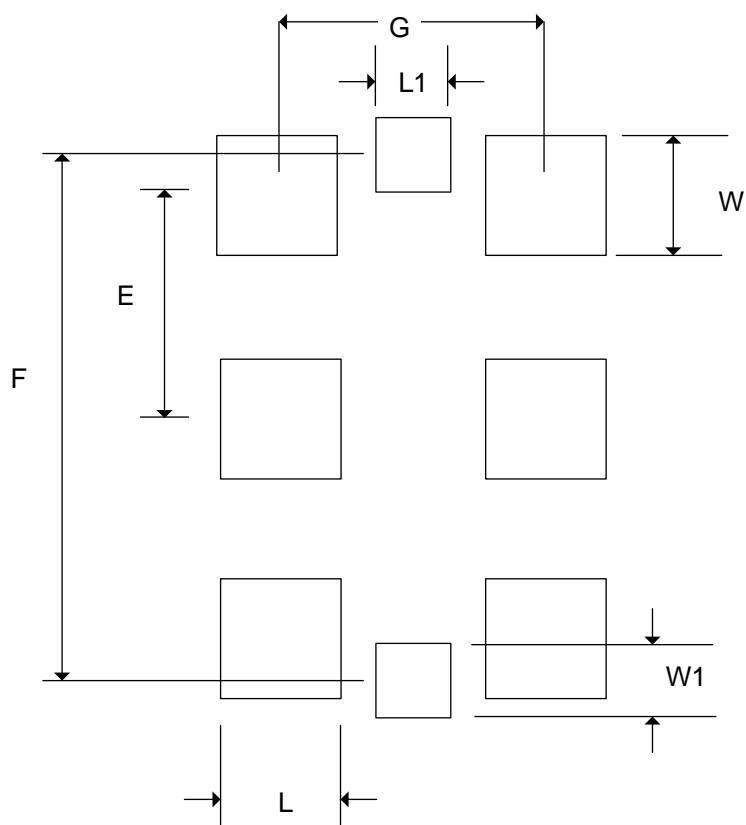


Figure 14. MS1510 Packaging Land Pattern Drawing (3.2mm x 2.5mm)

Table 9. MS1510 Packaging Land Pattern Dimensions

Dimensions	In mm
L	0.7
W	0.7
L1	0.5
W1	0.55
E	1.1
F	2.6
G	1.76

Device Top Marking

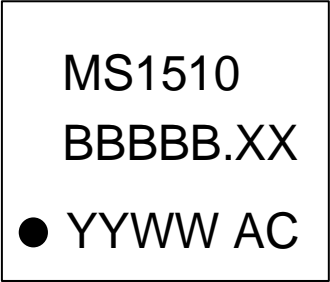


Figure 15. MS1510 Device Top Marking Showing Pin 1

Table 10. MS1510 Device Marking Legend

Line	Position	Description
1	1	Part Number
2	1-5	Wafer Lot Number
	6-7	Wafer #
3	Lot Traceability	
	1	Pin 1 Orientation Mark (Dot),
	2-3	Year (last two digit of the year)
	4-5	Calendar Work Week Number (1-53)
	6-7	Assembly Code

Part Ordering Information

Figure 16 shows a logic tree for ordering each of the three available parts.

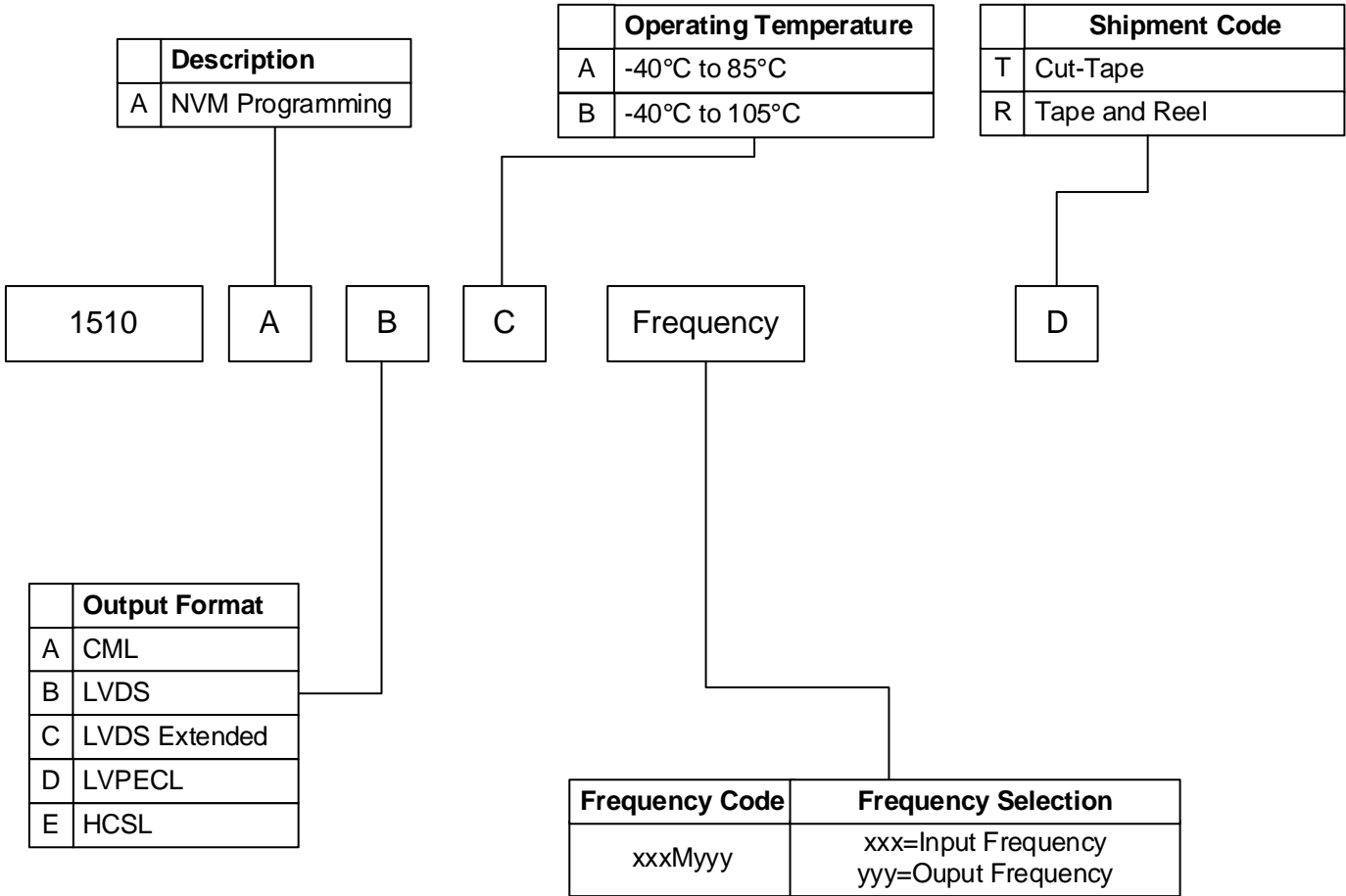


Figure 16. MS1510 Part Ordering Information

Input/Output Frequency codes for ordering

Code (xxx)	Frequency (MHz)	Code (yyy)	Frequency (MHz)
001	1	100	100
100	100	106	106.25
106	106.25	122	122.88
122	122.88	153	153.6
153	153.6	156	156.25
156	156.25	212	212.5
212	212.5	245	245.76
245	245.76	250	250
250	250	307	307.2
307	307.2	312	312.5
312	312.5	322	322.2656525
322	322.2656525	491	491.52
491	491.52	500	500
500	500	614	614.4
614	614.4	625	625
625	625	644	644.53125
644	644.53125	983	983.05
750	750	C50	1250

Please contact Mixed-Signal Devices for additional frequency codes

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